





NOTES:

- MATERIAL:  
 HOUSING: THERMOPLASTIC, UL 94V-0, COLOR: MOLDED BLACK  
 SPACER: THERMOPLASTIC, UL 94-0, COLOR: MOLDED BLACK  
 CONTACT: COPPER ALLOY  
 BOARDLOCK: COPPER ALLOY
- FINISH:  
 CONTACT : 1.27µM MIN. NICKEL UNDERPLATED OVERALL, TIN PLATED 100µin TO 200µin AT SOLDERTAIL AND GOLD PLATED 30µin AT CONTACT AREA  
 BOARDLOCK: 0.76µM MIN. NICKEL UNDERPLATED OVERALL, TIN PLATED 100µin TO 200µin
- HEIGHT OF GATE MARK SHOULD BE WITHIN 0.10MM
- FLASH 0.10 MAX, PARTING LINE MISMATCH 0.1 MAX

△ SOLDERTAIL POSITION SHALL BE CHECKED WITH GAUGE.

OBS. TIN/LEAD P/N EC NO. S2006-0729 DRAWN BY: DRW:WHLONG CHKD:SHONG APPR:KCLING 2006/02/27 2006/02/27 2006/02/28	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY RSHAN	DATE 2000/09/28	TITLE LIO CONNECTOR, 40 CKTS R/A, T/H			
REV	DESCRIPTION	4 PLACES	± ---	± ---	CHECKED BY SQUEK	DATE 2000/11/01	MOLEX INCORPORATED		
		3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2000/11/02			
		2 PLACES	± 0.2	± ---	MATERIAL NO. SD-87635-001		DOCUMENT NO. SD-87635-001	SHEET NO. 2 OF 2	
		1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
		ANGULAR ± 1 °		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			